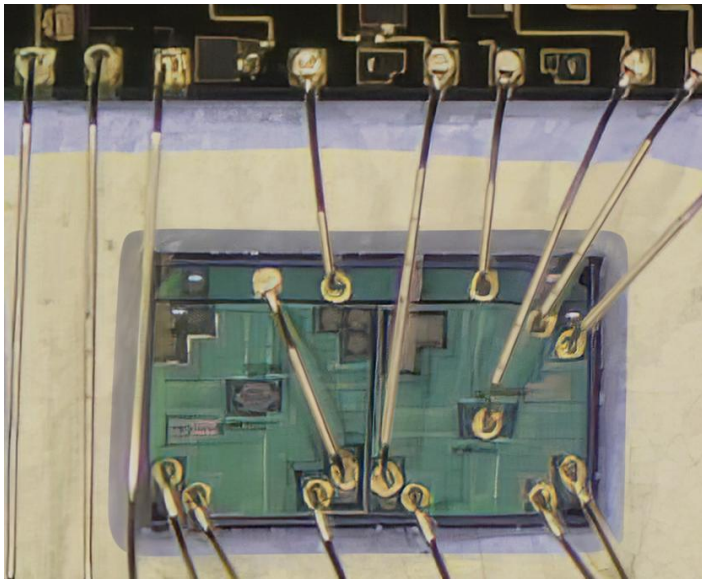


*For Immediate Release*

## Microsembly Furthers RF Hybrid Manufacturing Services with New Automated Wire Bonding and Die Attach Equipment



**Merrimack, NH – May 29, 2025** – Microsembly, a US-based provider of high-frequency contract manufacturing services, has announced the addition of new state-of-the-art automated and manual wire and ribbon bonders to its advanced RF and microwave assembly, manufacturing, and testing facility. This investment significantly enhances Microsembly’s fine-pitch interconnect and high-power bonding capabilities—supporting expanding customer demand across aerospace, defense, medical, and telecom markets.

The expanded in-house wire bonding and die attach suite now includes **Hesse Bondjet BJ855 and BJ820 automated wire bonders**, **Westbond 7KE/7KEH and 7476E/747630E manual wedge, ball, and ribbon bond bonders**, and a **Besi Datacon 2200 Evo Bonder**. They’ve also added a **Palomar SST 5100 Vacuum Pressure Furnace** for void free eutectic die attach.

With this equipment, Microsembly delivers a full spectrum of **wire bonding** and **die attach** services for the manufacturing of RF/microwave PCBAs used in complex mixed technology RF/microwave assemblies.

Wire and Ribbon Bonding and Die Attachment capabilities enabled by these systems include:

- **Gold (Au) ribbon bonds as small as .002” x .0005”**
- **Au wedge bonds down to .0007” on FETs, MMICs**
- **Au ball bonds and stitch-on-ball (SOB) bonds down to .0007”**
- **Quad diode package bonding with Au ribbon bonds down to .003” x .00025”**
- **Conductive epoxy die attach bond line thicknesses as little as .002”**

- **Combination bonds including ball, stitch-on-ball, and ribbon bonding**
- **Omega wrap (Double-C) ribbon bonds on feedthroughs**
- **Beam lead tacking with waffle patterning**
- **Cross bond stitching on ultra-small mesa diodes**
- **Precise MMIC-to-capacitor interconnects**
- **Void Free Eutectic Die Attach**

*“These machines not only add speed and repeatability but also allow our technicians to perform extremely precise and specialized bonds critical to high-reliability systems,” said Phuong “Kent” Dang, President at Microsembly. “From ultra-fine interconnects on microwave dies to rugged ribbon bonds on high-power components, we can handle a wide range of RF and microwave assembly challenges with confidence.”*

This enhanced wire bonding and die attach suite supports Microsembly’s vertically integrated model, offering everything from initial design and prototyping to high-frequency testing and full-volume production. Customers benefit from rapid development cycles, U.S.-based manufacturing, and proven quality assurance processes built for mission-critical environments.

#### About Microsembly

Microsembly is a US-based, ISO registered provider of RF and microwave contract design, manufacturing, assembly, and testing services. Supporting aerospace, defense, satellite, and high-frequency commercial markets, Microsembly specializes in high-reliability builds for Integrated Microwave Assemblies (IMAs), Multi-Chip Modules (MCMs), Sensor Chip Assemblies (SCAs), and System-in-Package (SiP) solutions. The company’s capabilities span design for manufacturability, microelectronics assembly, secure procurement, advanced RF testing, and post-deployment support.

**For more information, visit [www.microsembly.com](http://www.microsembly.com) or email [info@microsembly.com](mailto:info@microsembly.com).**

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